

What is claimed is:

1. An apparatus for testing ball grid arrays ("BGAs")  
5 comprising:  
a socket slot in a printed circuit board for holding a  
socket used for testing the BGAs; and  
plural holding members that support BGA solder balls.
2. The apparatus of Claim 1, wherein the socket top may  
10 have plural prong like holding members for supporting the solder  
balls.
3. The apparatus of Claim 1, wherein the socket top may  
have plural circular holding members for supporting the solder  
balls.
- 15 4. The apparatus of Claim 1, wherein the socket top may  
have plural spiral holding members for supporting the solder  
balls.
5. The apparatus of Claim 1, wherein the holding members  
may be etched on a BGA socket top.

6. The apparatus of Claim 1, wherein the holding members are flexible, rigid and/or semi-rigid to provide support for the solder balls.